

(Temperature=25°C)

Parameter		Symbol	Value	Unit
LED	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1 ^①	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Detector	Output Voltage	V_O	35	V
	Supply Voltage	V_{CC}	35	V
	Power Dissipation	P_C	400	mW
Isolation Voltage		V_{iso}	5000 ^②	Vrms
Operating Temperature		T_{opr}	-40~110	°C
Junction Temperature		T_j	125	°C
Storage Temperature		T_{stg}	-55~125	°C
Total Power Dissipation		P_{tot}	500	mW
Soldering Temperature		T_{sol}	260	°C

: 100μs pulse, 100Hz frequency

: AC for 1minute, R.H.=40~60%

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10mA$	-	1.35	1.6	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA
	Terminal Capacitance	C_t	$V=0, f=1MHz$	-	60	-	pF
Output	Peak High-level Output Current	I_{OPH}	$V_O=V_{CC}-4V,$ Pulse width 50μs	-1	-	-	A
			$V_O=V_{CC}-15V,$ Pulse width 10μs	-2.5	-	-	A
	Peak Low-level Output Current	I_{OPL}	$V_O=V_{EE}+2.5V,$ Pulse width 50μs	1	-	-	A
			$V_O=V_{EE}+15V,$ Pulse width 10μs	2.5	-	-	A
	High Level Supply Current	I_{CCH}	$I_F=10mA$ $V_{CC}=30V,$ $V_O=Open$	-	1.2	2	mA
	Low Level Supply Current	I_{CCL}	$I_F=0mA,$ $V_{CC}=30V,$	-	1.1	2	mA

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Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to High Output Level	t_{PLH}	$R_g=47 \Omega$, $C_g=3nF$, $I_F=0.5mA$, $V_{CC}=30V$	30	-	500	ns
Propagation Delay Time to Low Output Level	t_{PHL}	$R_g=47 \Omega$, $C_g=3nF$, $I_F=5.0mA$, $V_{CC}=30V$	30	-	500	
Propagation Delay Difference Between Any Two Parts	$t_{PHL} - t_{PLH}$	$R_g=47 \Omega$, $C_g=3nF$, $I_F=0.5mA$, $V_{CC}=30V$	-	-	350	
Output Rise Time (10 to 90%)	t_r	$R_g=47 \Omega$, $C_g=3nF$, $I_F=0.5mA$, $V_{CC}=30V$	-	50	-	
Output Fall Time (90 to 10%)	t_f	$R_g=47 \Omega$, $C_g=3nF$, $I_F=5.0mA$, $V_{CC}=30V$	-	50	-	
Common Mode Transient Immunity at High Level Output	$ CM_H $	$I_F=5mA$ $V_{CC}=30V$, $T_a=25^\circ C$, $V_O(min)=26V$ $V_{CM}=1000V_{pp}$	± 20	± 25	-	kV/ μs
Common Mode Transient Immunity at Low Level Output	$ CM_L $	$I_F=0mA$ $V_{CC}=30V$, $T_a=25^\circ C$, $V_O(max)=1V$ $V_{CM}=1000V_{pp}$	± 20	± 25	-	kV/ μs

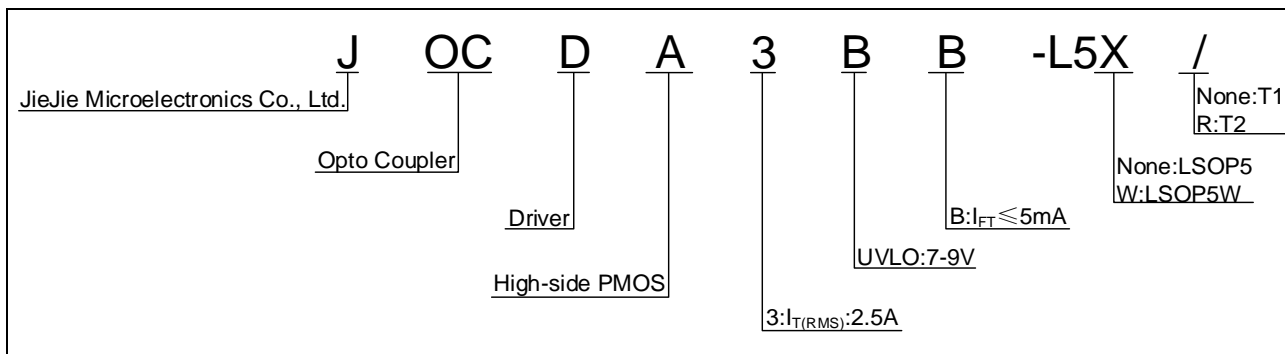
All Typical values at $T_a=25$

: Input signal ($f=25kHz$, $duty=50\%$, $t_r=t_f=5ns$ or less). C_L is less than 15 pF which includes probe and stray wiring capacitance.

: CM_H is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state ($V_O > 26V$).

: CM_L is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state ($V_O < 1V$).

	Max.	Unit
	10	mA
	0.8	V
	30	V



<p>None/R</p>	<p>3000 Units/Reel</p>

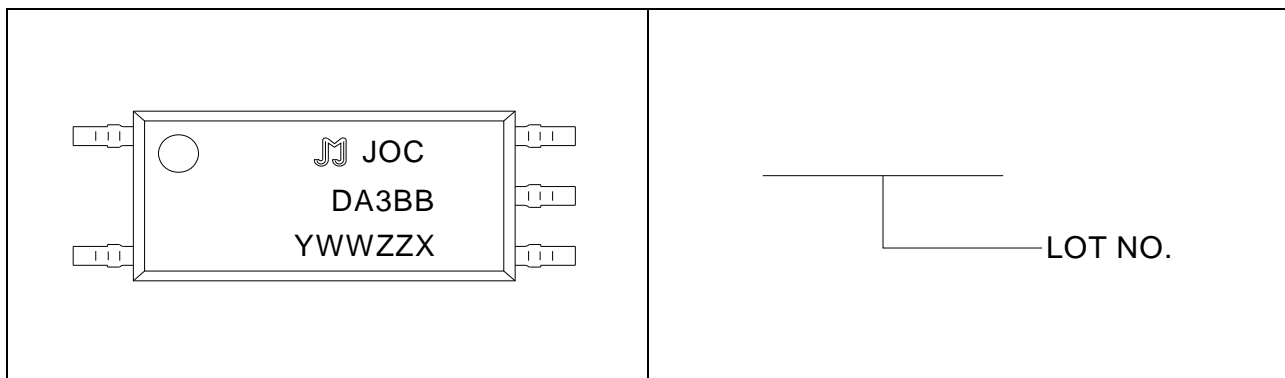


FIG.1: Forward Current vs. Forward Voltage



FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Low-level Output Voltage vs. Ambient Temperature

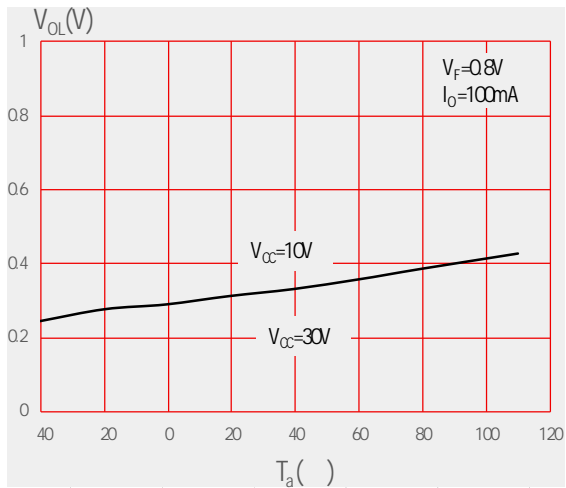


FIG.8: High-level Output Voltage vs. Ambient Temperature

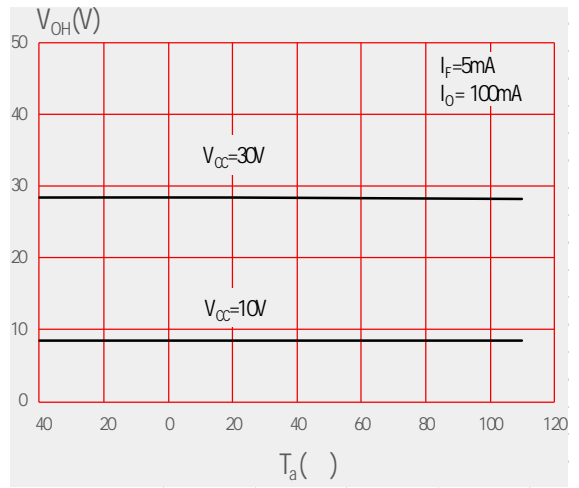


FIG.9: Low-level Output Voltage vs. Peak Low-level Output Current

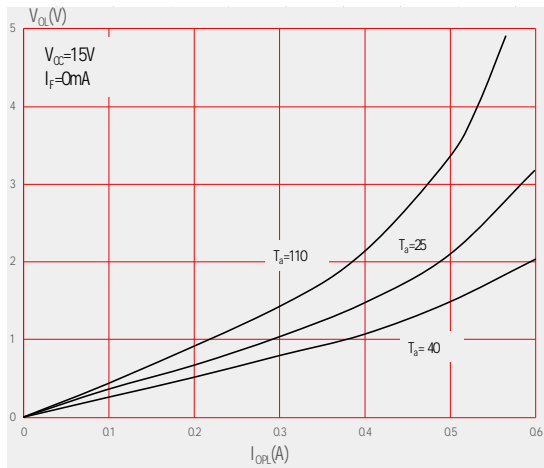


FIG.10: High-level Output Voltage Drop vs. Peak High-level Output Current

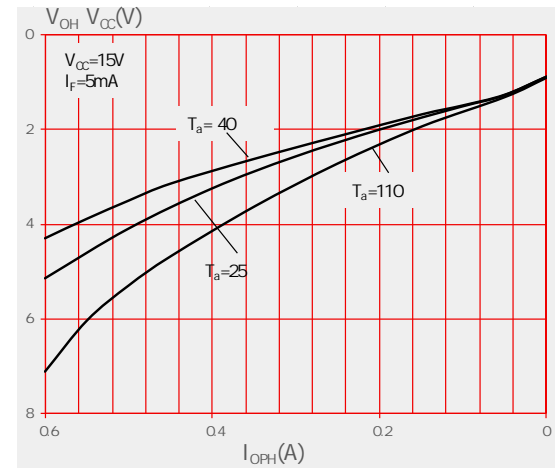


FIG.11: Propagation Delay Time, Pulse Width Distortion vs. Ambient Temperature

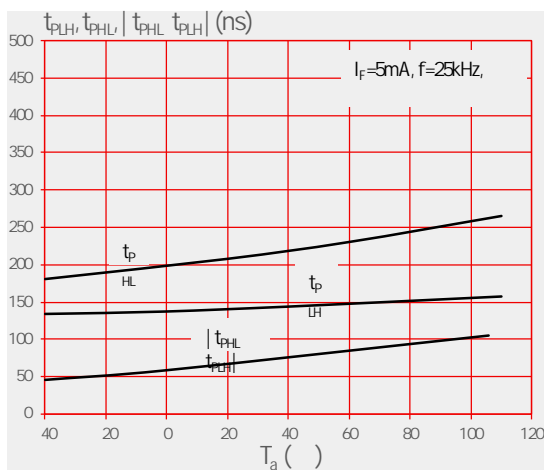


FIG.12: Propagation Delay Time, Pulse Width Distortion vs. Forward Current

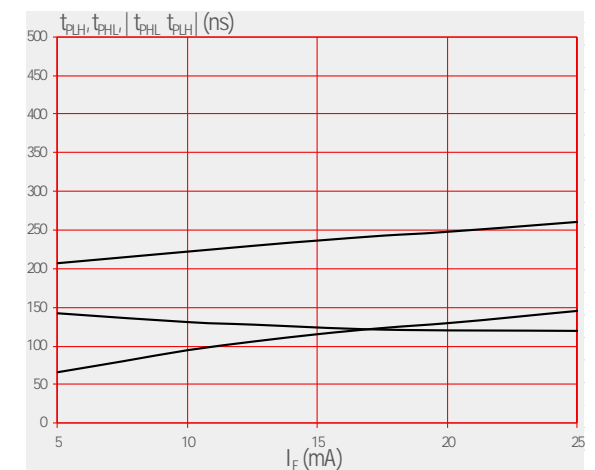


FIG.13: Propagation Delay Time, Pulse Width Distortion vs. Supply Voltage

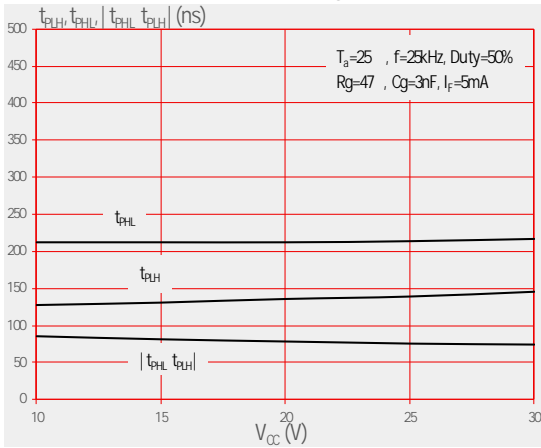


FIG.14: Switching Time Test Circuit and Waveform

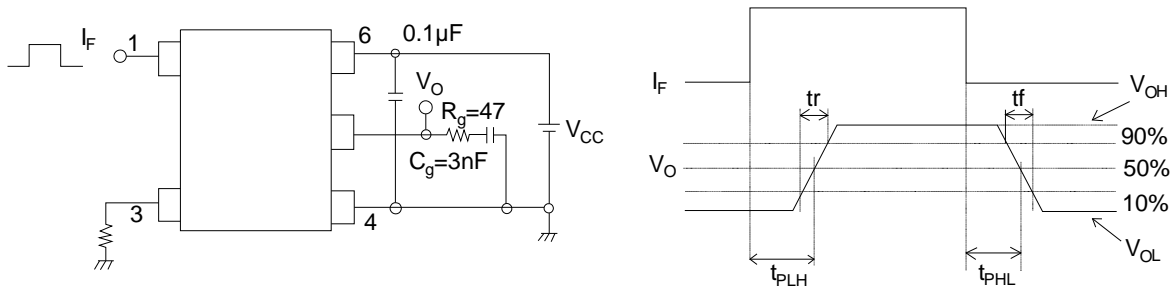
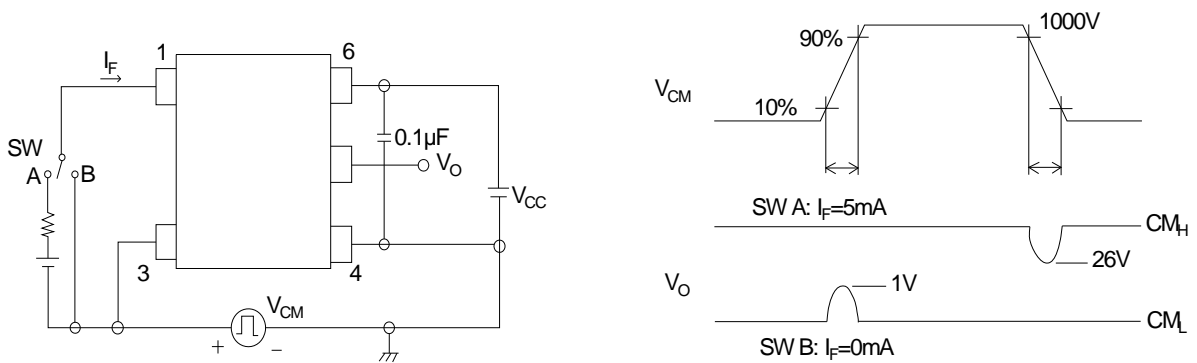
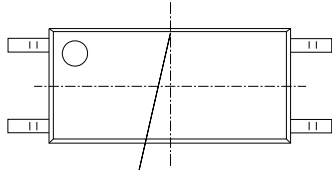
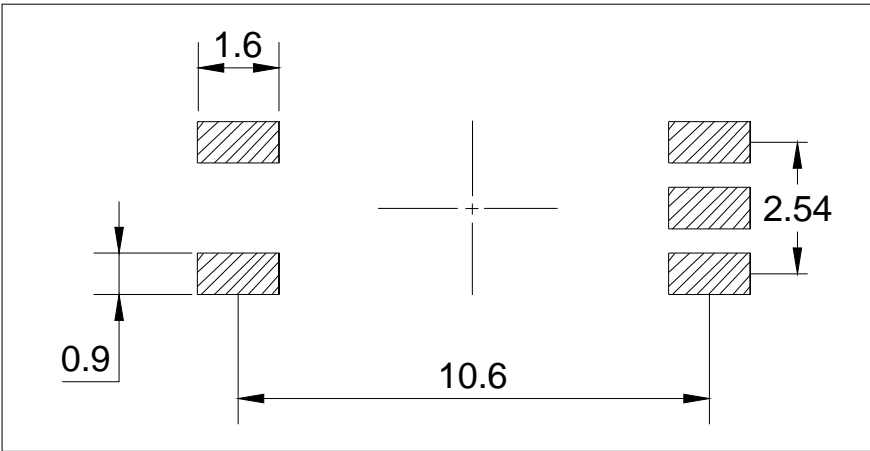


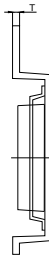
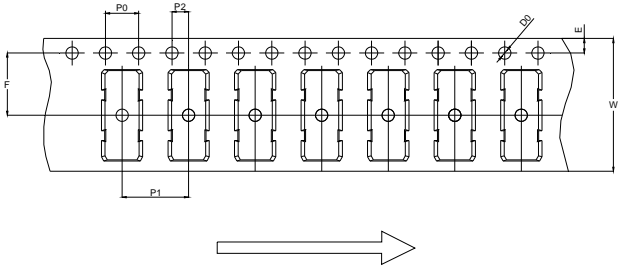
FIG.15: Common-Mode Transient Immunity Test Circuit and Waveform



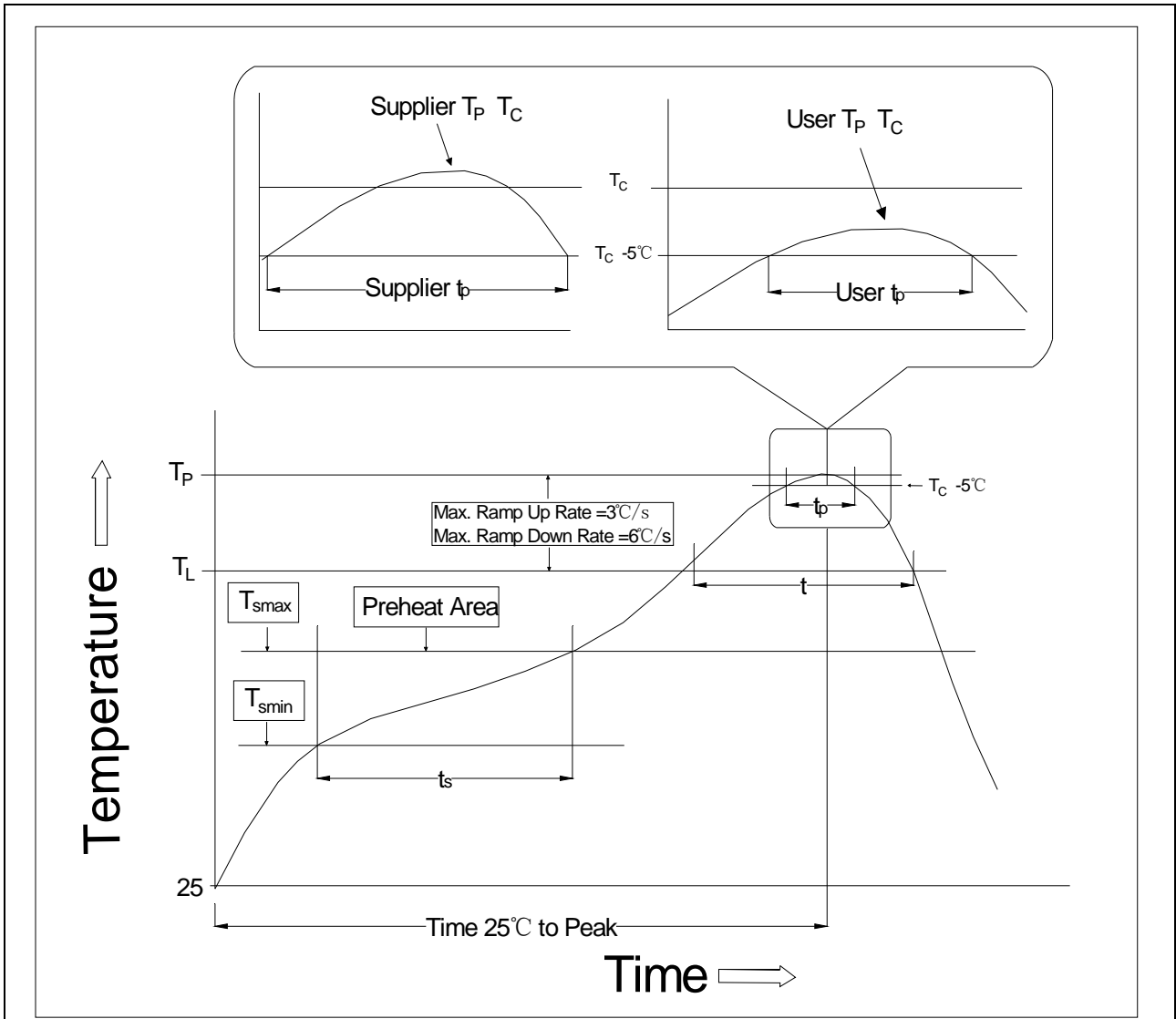


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K						





Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.50	1.55	1.60	0.059	0.061	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.80	16.00	16.20	0.622	0.630	0.638




Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100	150°C
Temperature Max. (T_{smax})	150	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T_L)	183°C	217°C
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t_P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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